



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C101JBANNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100pF, 50V, ±5%, C0G, 0805

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>101</u> <u>J</u> <u>B</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Se	eries	Samsung Multi-layer Ceramic Capacitor										
② Siz	ze	0805	(inch co	ode)	L:	2.0	± 0.1	mm	W:	1.25	± 0.1	mm
3 Die	electric	C0G				8	Inner ele	ctrode		Ni		
4 Ca	pacitance	100	рF				Terminat	tion		Cu		
⑤ Ca	pacitance	±5	%				Plating			Sn 10	0%	(Pb Free)
tol	lerance					9	Product			Norma	al	
⑥ Ra	ited Voltage	50	V			10	Special			Reser	ved for	future use
⑦ Th	ickness	0.65	± 0.1	mm		11)	Packagir	ng		Cardb	oard T	ype, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms
Q	1000 min	
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.
Resistance	Whichever is Smaller	
Appearance	No abnormal exterior appearance	Microscope (×10)
Withstanding	No dielectric breakdown or	300% of the rated voltage
Voltage	mechanical breakdown	
Temperature	COG	
Characterisitcs	(From -55 $^{\circ}$ to 125 $^{\circ}$ , Capacitance change	shoud be within ±30PPM/℃)
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.
of Termination	terminal electrode	
Bending Strength	Capacitance change :	Bending to the limit (1mm)
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder
	is to be soldered newly	245±5℃, 3±0.3sec.
		(preheating : 80~120℃ for 10~30sec.)
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.
Soldering heat	within ±2.5% or ±0.25pF whichever is larger	
	Tan δ, IR : initial spec.	

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q: 200 min						
	IR : 500Mohm or 25Mohm $\cdot \mu$ F						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature					
	Q: 350 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25 ℃					
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$					
		5 cycle test					

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.